





Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
	T_{LEB}			300		ns
	I_{PMAX}		300	330	360	mA
FB						
	V_{FB_REF}			1.2		V
	V					

/ Functional Description

BRAD6265DSC

PWM

BRAD6265DSC

CC/CV

90V~264V

TL431

/

BRAD6265DSC

CC

CV

FB

FB

BRAD6265DSC

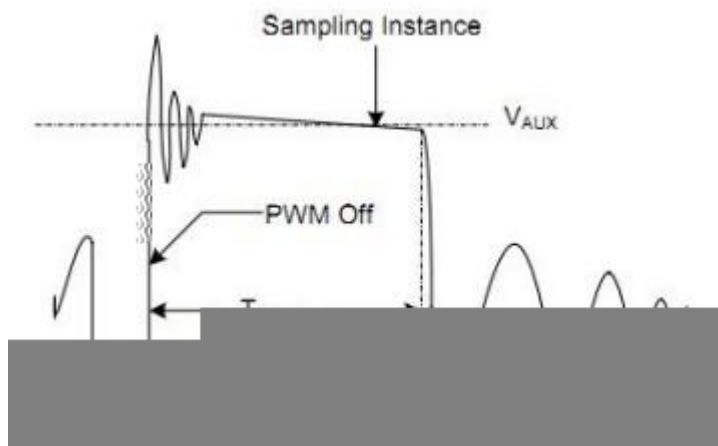
CC/CV

DCM

I_p

— 1

— 2



1

/ Functional Description

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† š fi — > † s 7 1 É % ^ © h È È Ì Í † ' Î Ï ~ % ? Ð (/ Ñ Ò / fi † s Ó > \$

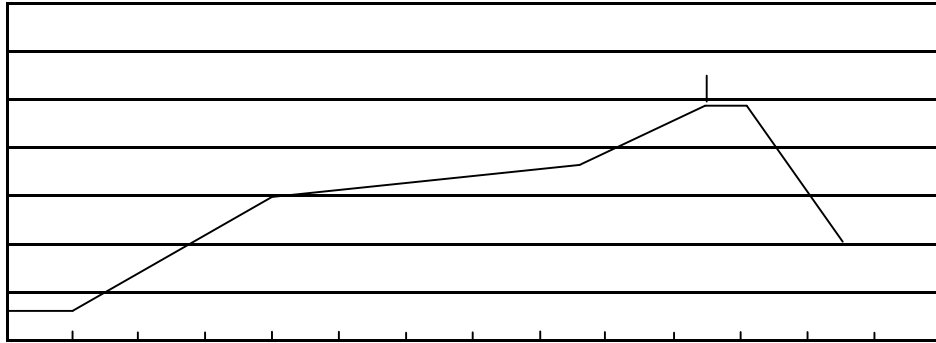
BRAD6265DSC ™ ² Ô 2 Ö Ö fi „ ² f „ 7 % & ¨ × Ø 2 Ù Ú Û \$ ½ Ü 2 Û Ü Ý Þ B ‡ ; d
mUVL On 7 VCC † ‡ à á 7 ´ â 2 Û mOTP n 7 ã ä å † s Ä Æ m OCP n 7 P Q æ ' 2 Û 7 % & È
È Ì Í † ' ç \$ \$ ~ è † ‡ é VCC † ‡ ‹ T ° è „ ~ è è 7 " VCC ì Á ž í B ‡ ; d fi ì ...† ‡ + 7
/ L 9 ï ð L N 7 ® \ Õ Ö ñ ò ž í Ø Ñ H I \$

PCB

© h BRAD6265DSC PCB + 7 ó ô õ ö † 5 A ÷ l
GND ø ù PCB ú z l \$ ~ % & CS † Ž 7 Õ Ö » Ä † s ü ï y GND s ü P í † ý 7 þ PCB ú z
ó ÿ œ æ ~ 7 \ í P í † ý F °
VCC † ý l T 2.2uF ~ X7R † ý 7 ‡ 6.3V ~ ì Ž † † ý 4.7uF/10V \$ VCC
fi † ý ó ô \$ ~ VCC ~ GND ø ù , \$ ~ VCC ø ù } ø z ´ ù ï ` \$ ~ VCC ø ù
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FB " # ø ù l 4 FB fi fl † ‡ Ž FB ø ù 7 É ø " ‡ ? Ç È „ fi ò 7 R „
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~ % b ' z l ~ % b ' fi 7 " ‡ ? ¹ C ¹ z † ý fi b ' 7 † " ‡ ? ¹ K s
~ € M ¹ P Q † ý fi b ' 7 EMI ³ ´ \$
F G ...l À T ? W VCC † ý e _ † ‡ 7 ó VCC _ d 7 É VCC > 3.3V + 7
F G Ž ... ó \$



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | |
|---|---------|-----------|--|
| 1 | 150 180 | 60 90sec; | 1.Preheating:150~180°C, Time:60~90sec. |
| 2 | 245±5 | 5±0.5sec; | 2.Peak Temp.:245±5°C, Duration:5±0.5sec. |
| 3 | 2 | 10°C/sec. | 3. Cooling Speed: 2~10°C/sec. |

/ Resistance to Soldering Heat Test Conditions

260±5°C 10±1 sec. Temp.:260±5°C Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOP-8	4,000	2	8,000	6	48,000	13 x12	360x360x50	380x335x366

/ Notices